

MBRM130LT3

Surface Mount Schottky Power Rectifier

POWERMITE® Power Surface Mount Package

The Schottky Powermite employs the Schottky Barrier principle with a barrier metal and epitaxial construction that produces optimal forward voltage drop–reverse current tradeoff. The advanced packaging techniques provide for a highly efficient micro miniature, space saving surface mount Rectifier. With its unique heatsink design, the Powermite has the same thermal performance as the SMA while being 50% smaller in footprint area, and delivering one of the lowest height profiles, < 1.1 mm in the industry. Because of its small size, it is ideal for use in portable and battery powered products such as cellular and cordless phones, chargers, notebook computers, printers, PDAs and PCMCIA cards. Typical applications are ac/dc and dc–dc converters, reverse battery protection, and “Oring” of multiple supply voltages and any other application where performance and size are critical.

Features:

- Low Profile — Maximum Height of 1.1 mm
- Small Footprint — Footprint Area of 8.45 mm²
- Low V_F Provides Higher Efficiency and Extends Battery Life
- Supplied in 12 mm Tape and Reel — 12,000 Units per Reel
- Low Thermal Resistance with Direct Thermal Path of Die on Exposed Cathode Heat Sink

Mechanical Characteristics:

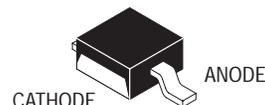
- Powermite is JEDEC Registered as D0–216AA
- Case: Molded Epoxy
- Epoxy Meets UL94, VO at 1/8”
- Weight: 62 mg (approximately)
- Device Marking: BCF
- Lead and Mounting Surface Temperature for Soldering Purposes. 260°C Maximum for 10 Seconds

This document contains information on a new product. Specifications and information herein are subject to change without notice.



ON Semiconductor
Formerly a Division of Motorola
<http://onsemi.com>

SCHOTTKY BARRIER RECTIFIER 1.0 AMPERES 30 VOLTS



**PLASTIC
CASE 457**

ORDERING INFORMATION

Device	Package	Shipping
MBRM130LT3	Plastic	12,000 Units per 12 mm Tape & Reel

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MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V_{RRM} V_{RWM} V_R	30	V
Average Rectified Forward Current (At Rated V_R , $T_C = 135^\circ\text{C}$)	I_O	1.0	A
Peak Repetitive Forward Current (At Rated V_R , Square Wave, 100 kHz, $T_C = 135^\circ\text{C}$)	I_{FRM}	2.0	A
Non-Repetitive Peak Surge Current (Non-Repetitive peak surge current, halfwave, single phase, 60 Hz)	I_{FSM}	50	A
Storage Temperature	T_{stg}	-55 to 150	$^\circ\text{C}$
Operating Junction Temperature	T_J	-55 to 125	$^\circ\text{C}$
Voltage Rate of Change (Rated V_R , $T_J = 25^\circ\text{C}$)	dv/dt	10,000	V/ μs

THERMAL CHARACTERISTICS

Thermal Resistance – Junction-to-Lead (Anode) (1)	R_{tjl}	35	$^\circ\text{C/W}$
Thermal Resistance – Junction-to-Tab (Cathode) (1)	R_{tjtab}	23	
Thermal Resistance – Junction-to-Ambient (1)	R_{tja}	277	

(1) Mounted with minimum recommended pad size, PC Board FR4, See Figures 9 & 10.

ELECTRICAL CHARACTERISTICS

Maximum Instantaneous Forward Voltage (2), See Figure 2 ($I_F = 0.1\text{ A}$) ($I_F = 1.0\text{ A}$) ($I_F = 3.0\text{ A}$)	V_F	$T_J = 25^\circ\text{C}$	$T_J = 85^\circ\text{C}$	V
		0.30	0.20	
		0.38	0.33	
Maximum Instantaneous Reverse Current, See Figure 4 ($V_R = 30\text{ V}$) ($V_R = 20\text{ V}$) ($V_R = 10\text{ V}$)	I_R	$T_J = 25^\circ\text{C}$	$T_J = 85^\circ\text{C}$	mA
		0.41	11	
		0.13	5.3	
		0.05	3.2	

(2) Pulse Test: Pulse Width $\leq 250\ \mu\text{s}$, Duty Cycle $\leq 2\%$.

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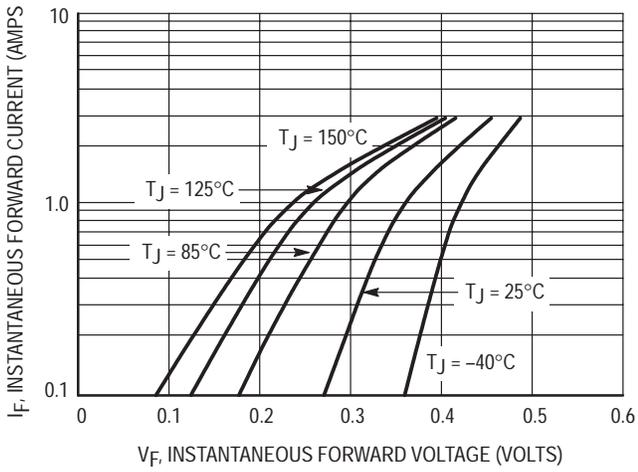


Figure 1. Typical Forward Voltage

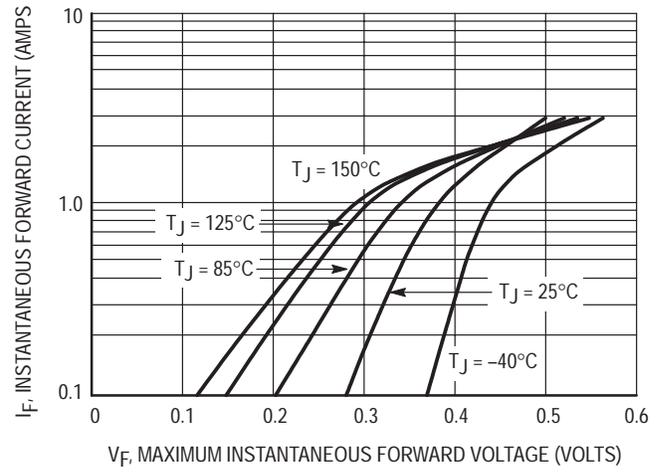


Figure 2. Maximum Forward Voltage

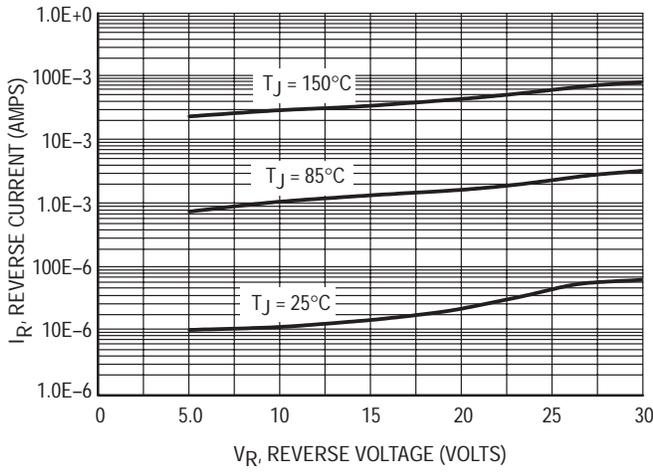


Figure 3. Typical Reverse Current

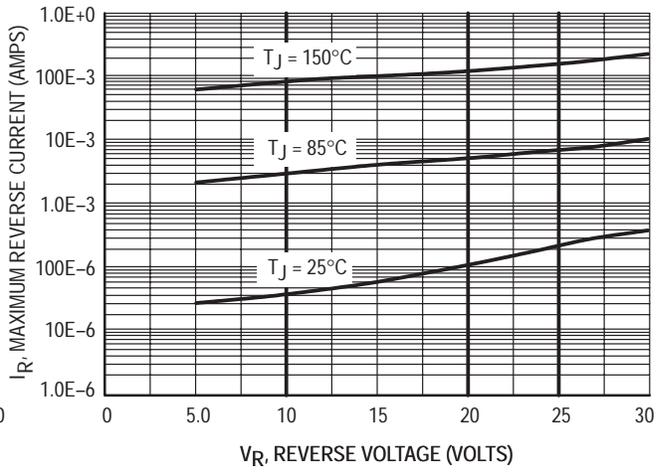


Figure 4. Maximum Reverse Current

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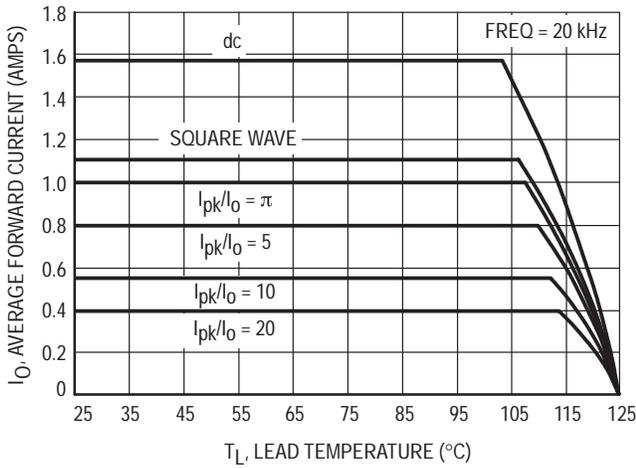


Figure 5. Current Derating

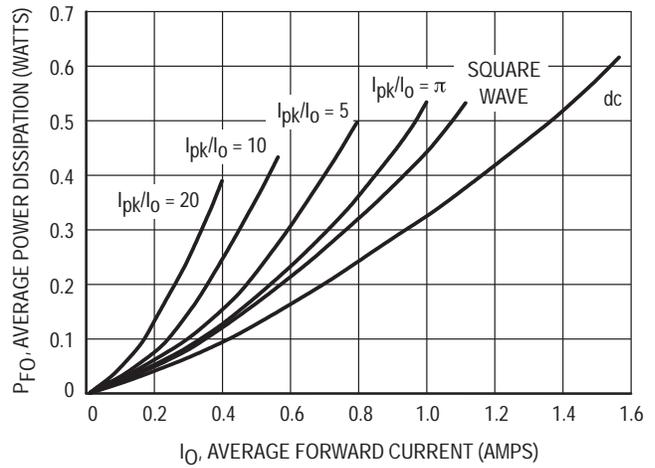


Figure 6. Forward Power Dissipation

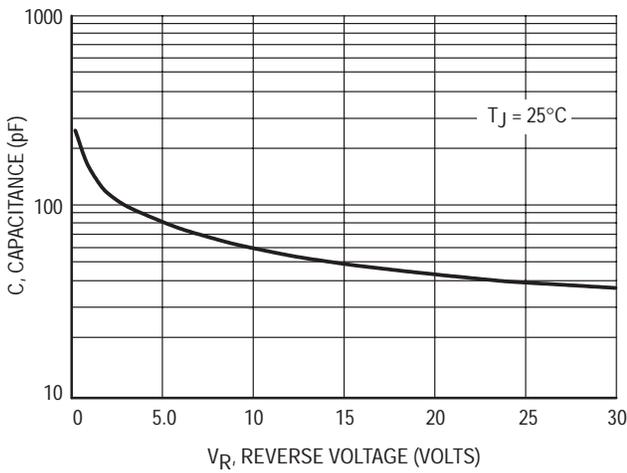


Figure 7. Capacitance

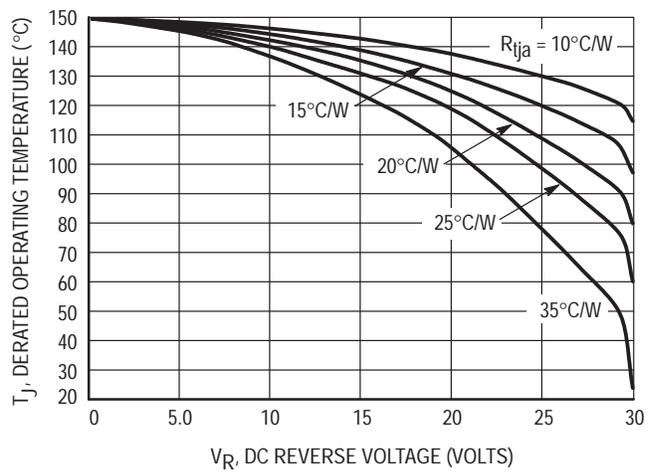


Figure 8. Typical Operating Temperature Derating*

* Reverse power dissipation and the possibility of thermal runaway must be considered when operating this device under any reverse voltage conditions. Calculations of T_J therefore must include forward and reverse power effects. The allowable operating T_J may be calculated from the equation:

$$T_J = T_{Jmax} - r(t)(P_f + P_r) \text{ where}$$

$r(t)$ = thermal impedance under given conditions,
 P_f = forward power dissipation, and
 P_r = reverse power dissipation

This graph displays the derated allowable T_J due to reverse bias under DC conditions only and is calculated as $T_J = T_{Jmax} - r(t)P_r$, where $r(t) = R_{thja}$. For other power applications further calculations must be performed.

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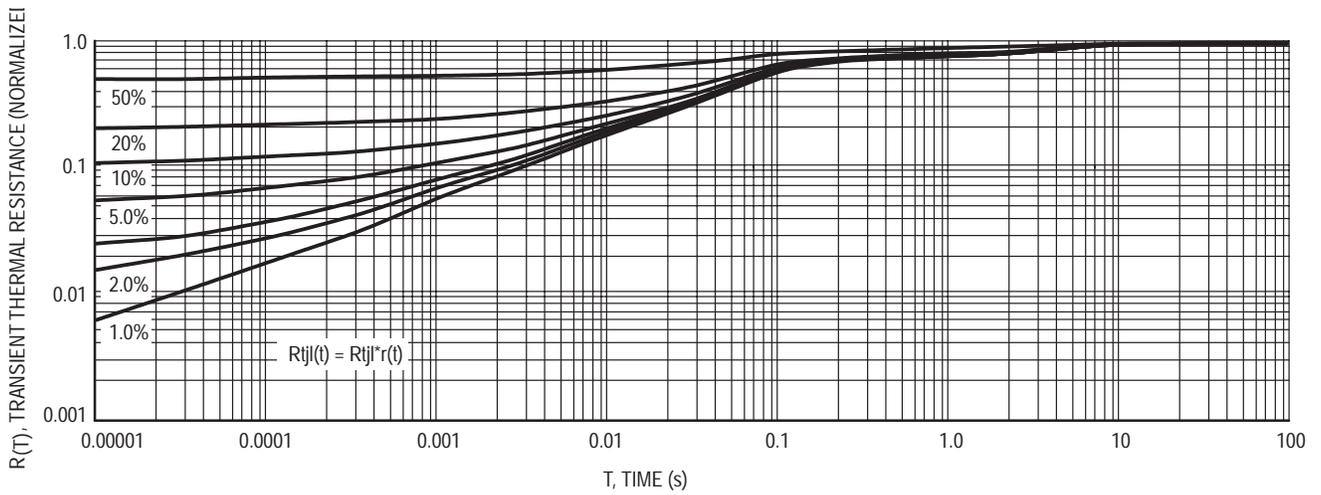


Figure 9. Thermal Response Junction to Lead

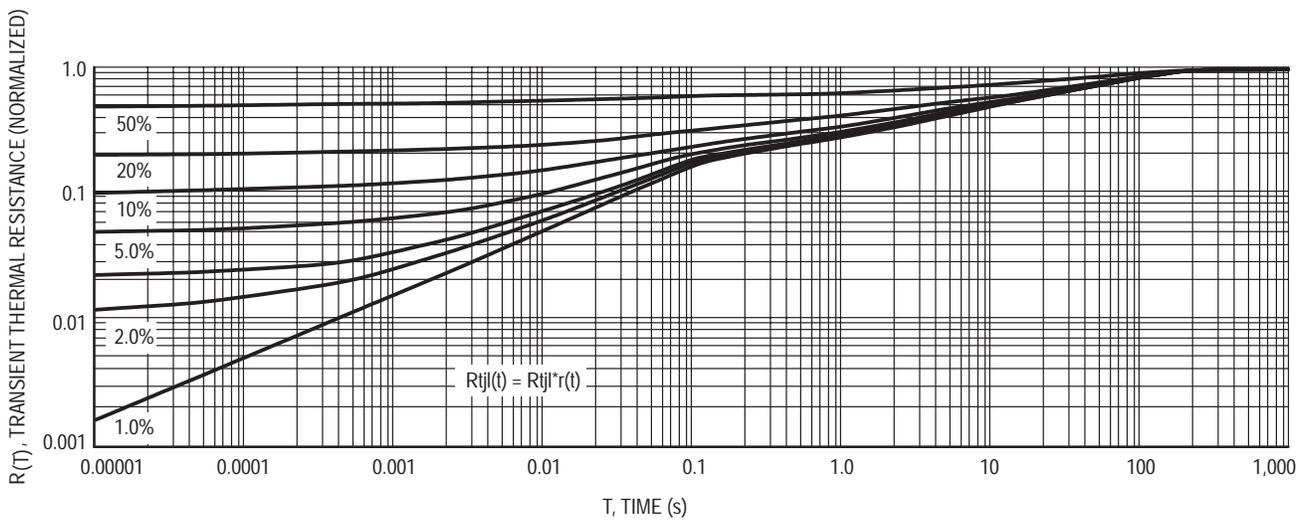
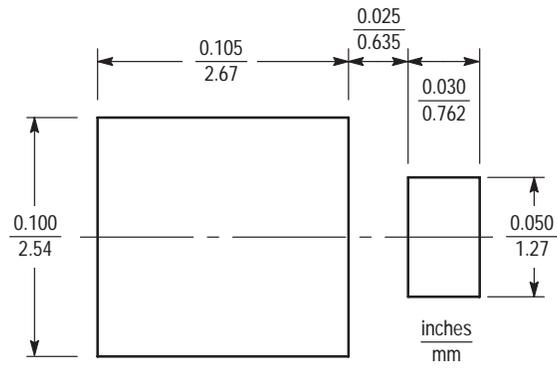


Figure 10. Thermal Response Junction to Ambient

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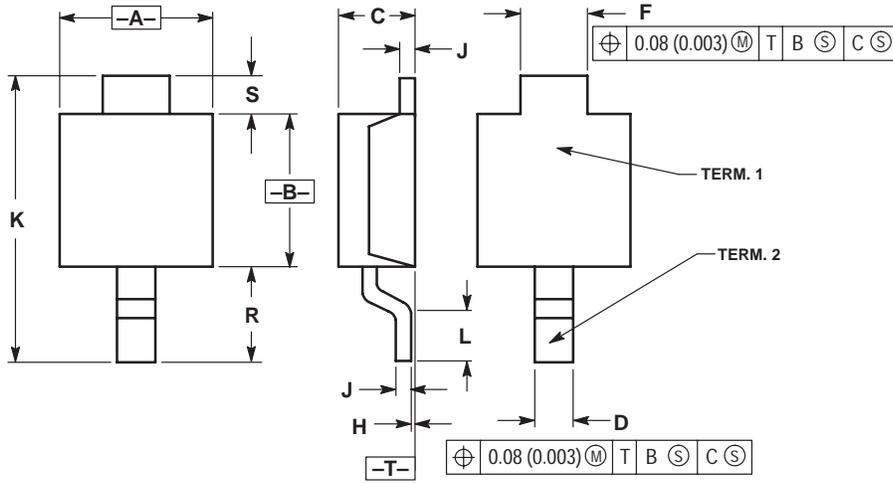


Minimum Recommended Footprint

MBRM130LT3

PACKAGE DIMENSIONS

N SUFFIX
 PLASTIC PACKAGE
 CASE 457-04
 ISSUE C



NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH, PROTRUSIONS OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	1.75	2.05	0.069	0.081
B	1.75	2.18	0.069	0.086
C	0.85	1.15	0.033	0.045
D	0.40	0.69	0.016	0.027
F	0.70	1.00	0.028	0.039
H	-0.05	+0.10	-0.002	+0.004
J	0.10	0.25	0.004	0.010
K	3.60	3.90	0.142	0.154
L	0.50	0.80	0.020	0.031
R	1.20	1.50	0.047	0.059
S	0.50	REF	0.019	REF

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German Phone: (+1) 303-308-7140 (M-F 2:30pm to 5:00pm Munich Time)

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Email: ONlit@hibbertco.com

ASIA/PACIFIC: LDC for ON Semiconductor – Asia Support

Phone: 303-675-2121 (Tue-Fri 9:00am to 1:00pm, Hong Kong Time)
Toll Free from Hong Kong 800-4422-3781

Email: ONlit-asia@hibbertco.com

JAPAN: ON Semiconductor, Japan Customer Focus Center
4-32-1 Nishi-Gotanda, Shinagawa-ku, Tokyo, Japan 141-8549

Phone: 81-3-5740-2745

Email: r14525@onsemi.com

Fax Response Line: 303-675-2167

800-344-3810 Toll Free USA/Canada

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